



Test-Beam Analysis of HGTD Prototype Modules for the ATLAS Phase-II Upgrade

***Karabo Tau¹,
Rachid Mazini¹, Roja Rimer¹, Thabo Lepota¹, Pau Fuste
Martin²***

¹University of the Witwatersrand,

²The Barcelona Institute of Science and Technology



Outline

1) Motivation:

The High Luminosity LHC

2) Introduction:

**HGTD Module (LGAD sensors &
HGTD Front-End ASIC)**

3) Timing in HGTD

4) Experimental setup:

**Test-beam campaigns,
Test-beam workflow**

5) Test-Beam measurements:

**Hit efficiency,
and Timing performance**

6) Conclusions

Motivation: The High Luminosity LHC

From July 2026, LHC will be upgraded and in 2030, LHC will run in "High Luminosity" (HL-LHC)

- Instantaneous **luminosity** will be approximately a factor of **~5-7.5** higher than the LHC nominal values
- Average number of interactions per bunch crossing (pileup events) reaches **200**
- The increased pile-up and radiation levels require detector upgrades capable of maintaining excellent tracking and timing performance in the forward region .

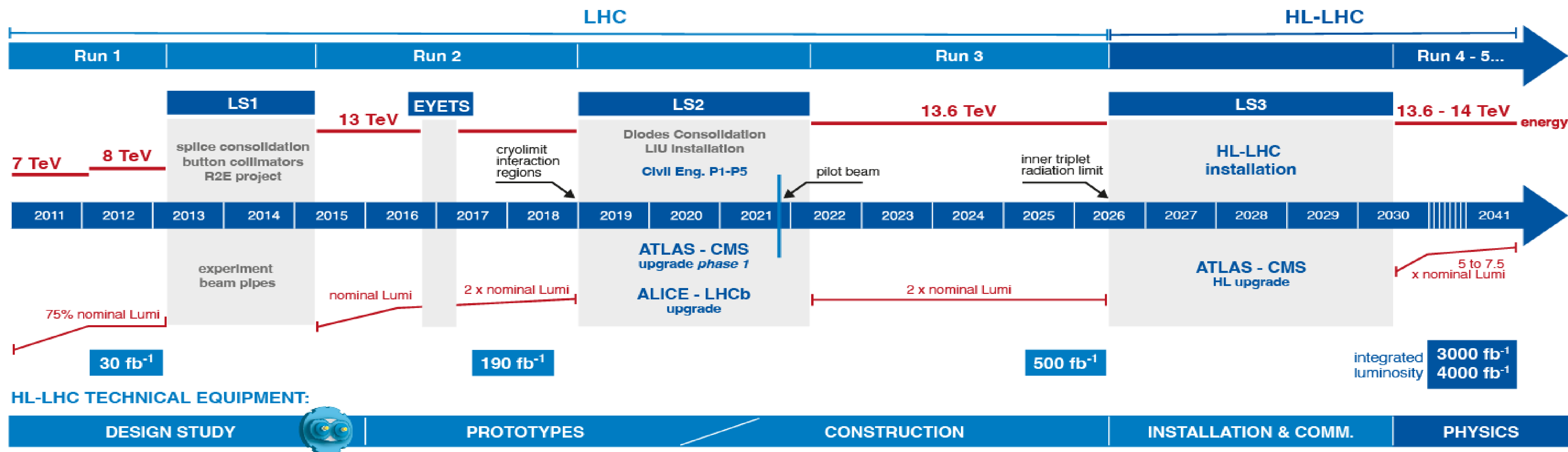


Figure 1: LHC/ HL-LHC Plan

Introduction: The High Granularity Timing Detector (HGTD)

- Dedicated **timing detector** for the forward region
- **Double-sided disks** between the new Inner Tracker (ITk) end-cap rings and the end-cap calorimeters
 - Location: $\pm 3.5\text{m}$ from the interaction point
 - Coverage: $120\text{ mm} < r < 640\text{ mm}$ & $2.4 < |\eta| < 4.0$
- The HGTD comprises **8032** modules
- Each HGTD module consists of LGAD sensors read out by ALTIROC ASICs
- Target time resolution:
~ **30 (50) ps per track beginning (end)** of HGTD lifetime
- Provide **bunch by bunch** luminosity measurements

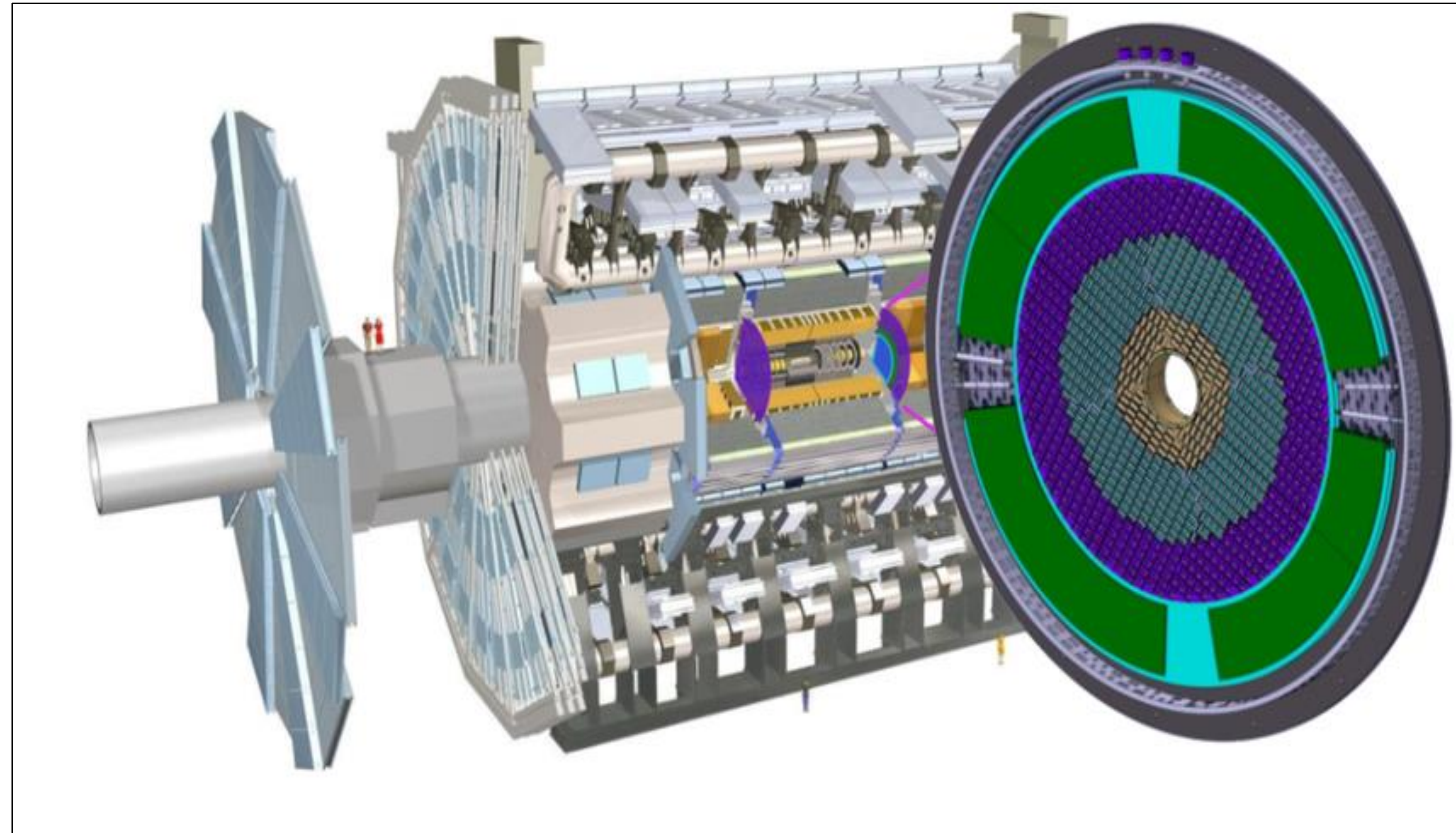


Figure 2: Position of the HGTD within the ATLAS Detector

Introduction: The HGTD LGAD sensor

Why LGADs?

- n-on-p structure with additional p-type gain layer
- Low gain (~ 10) for fast signal rise time and enhanced signal-to-noise ratio
- Fine segmentation (15×15 pads, 1.3 mm^2 per pad)
- Carbon-enriched gain layer for radiation hardness

HGTD Performance Targets:

- Collected charge: **> 10 (4) fC per MIP** before irradiation (after irradiation)
- Hit efficiency: **> 97% (>95%)** at the beginning of detector operation (end of detector lifetime)

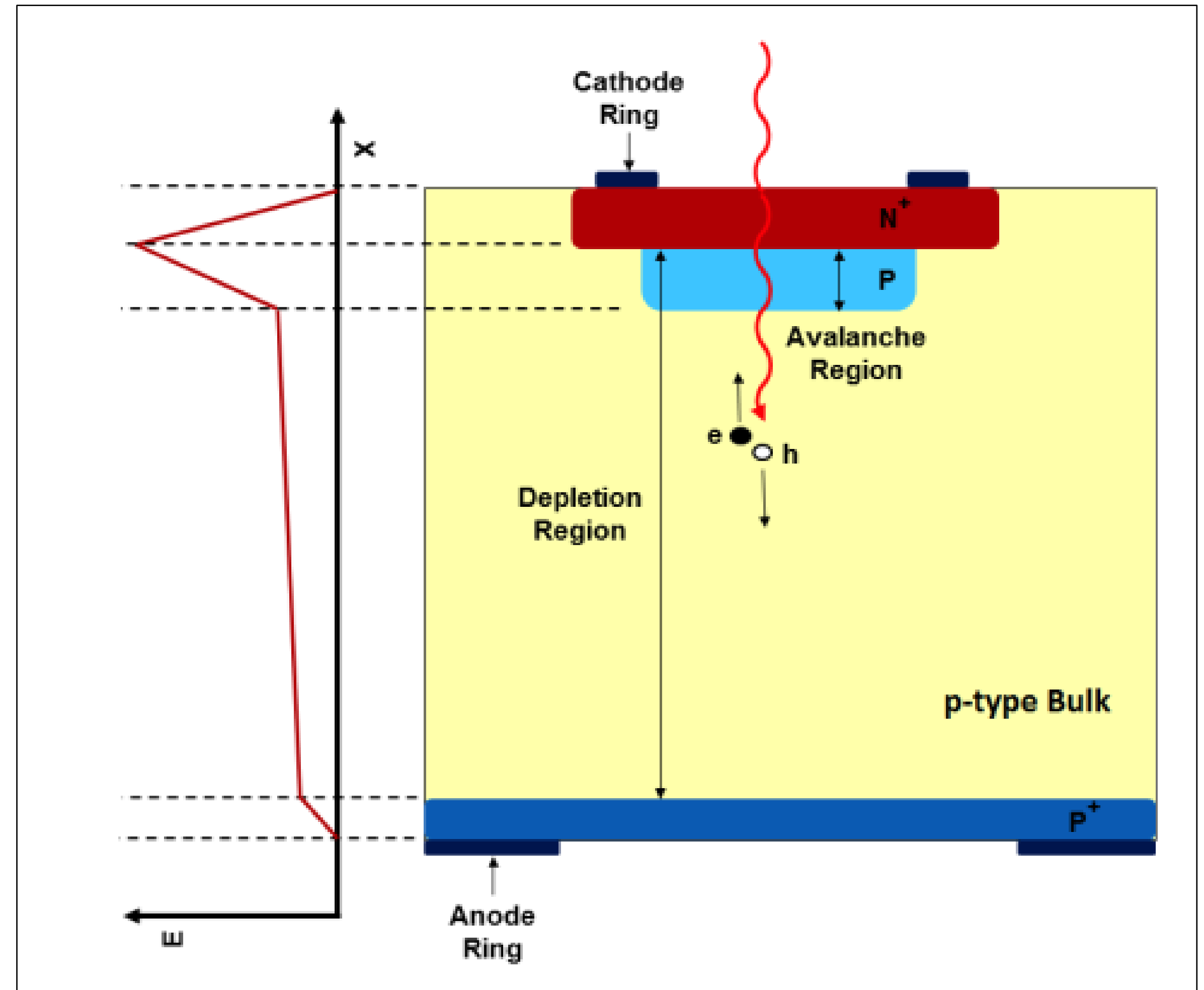


Figure 3: Cross section of an LGAD sensor

Introduction: HGTD Front-End ASIC (ALTIROC)

- **ALTIROC** (ATLAS LGAD Timing Read-Out Chips) are ASIC (Application-Specific Integrated Circuit) chips
- Designed to interface with the HGTD LGAD sensors
- **130nm** CMOS technology from TSMC
- **225** channels arranged in a **15×15** matrix

Provided measurements:

- Time-of-Arrival (ToA)
- Time-over-Threshold (ToT)

FINAL VERSION: ALTIROC-A

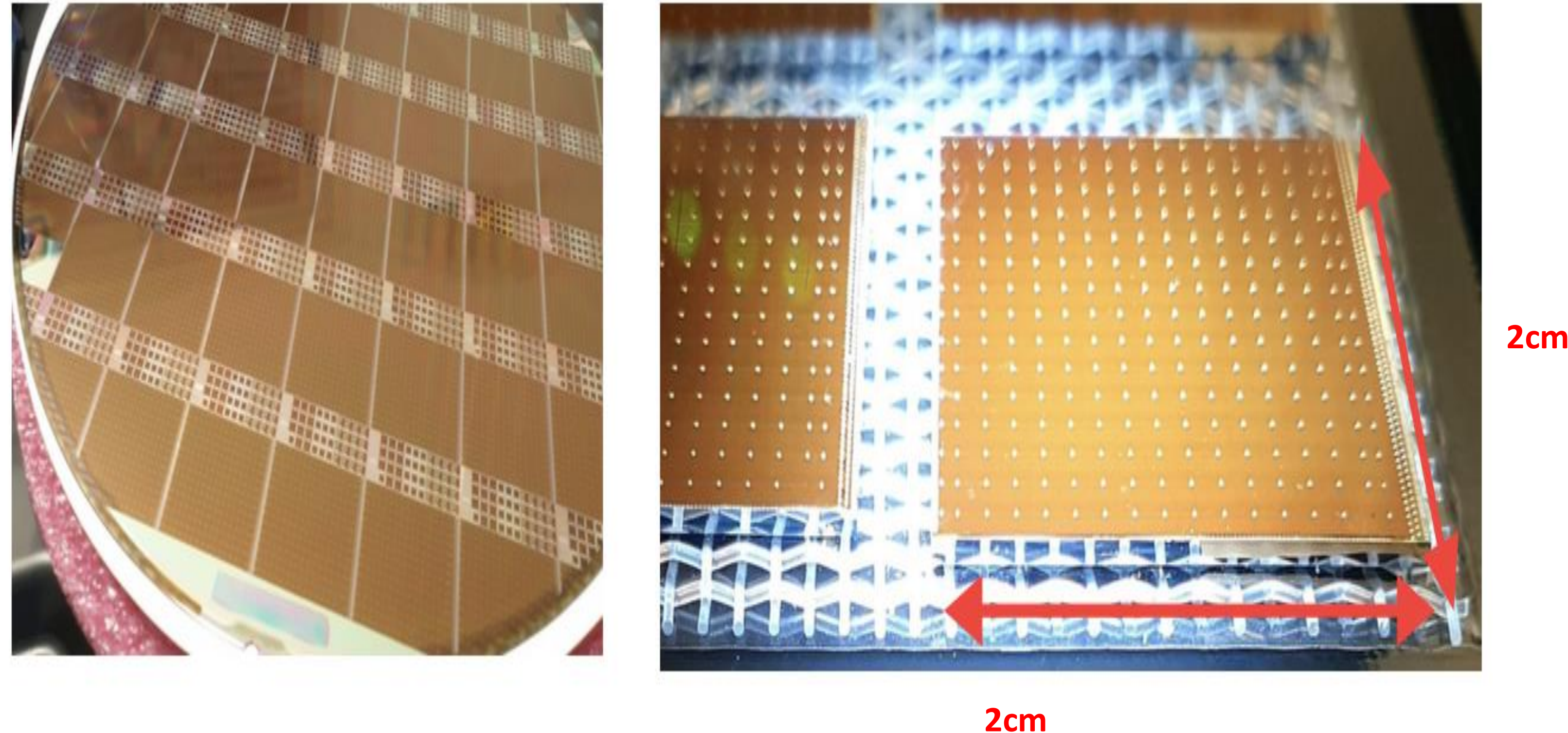


Figure 4: HGTD Front-End ASIC Chip: ALTIROC

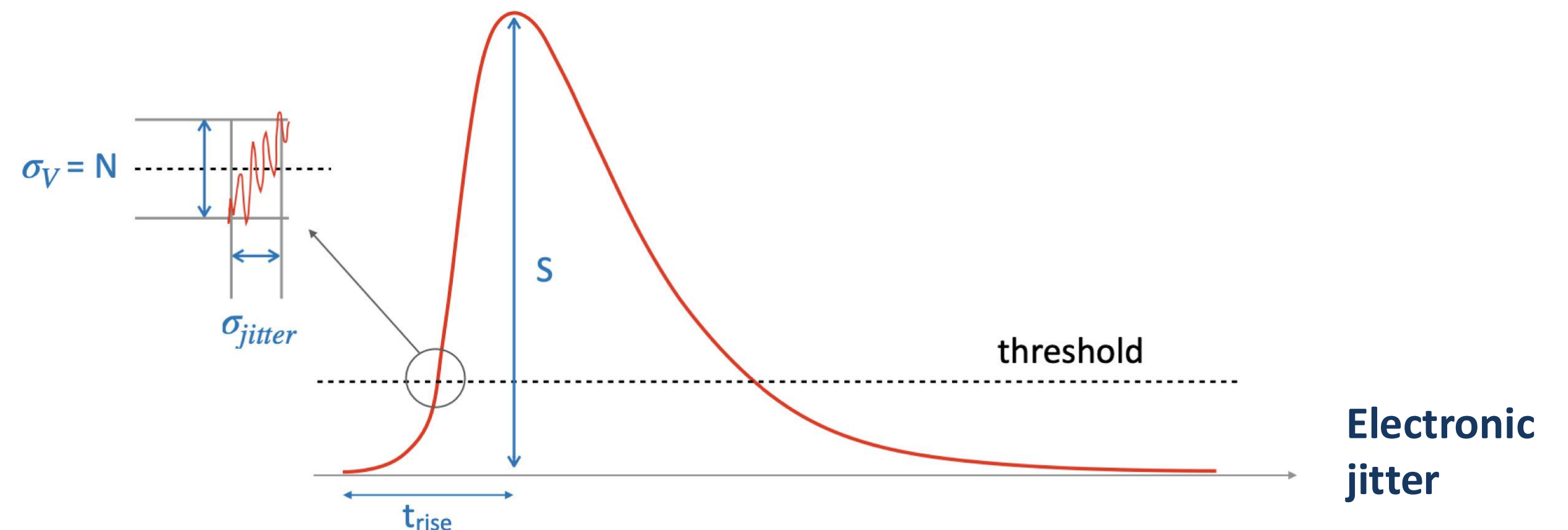
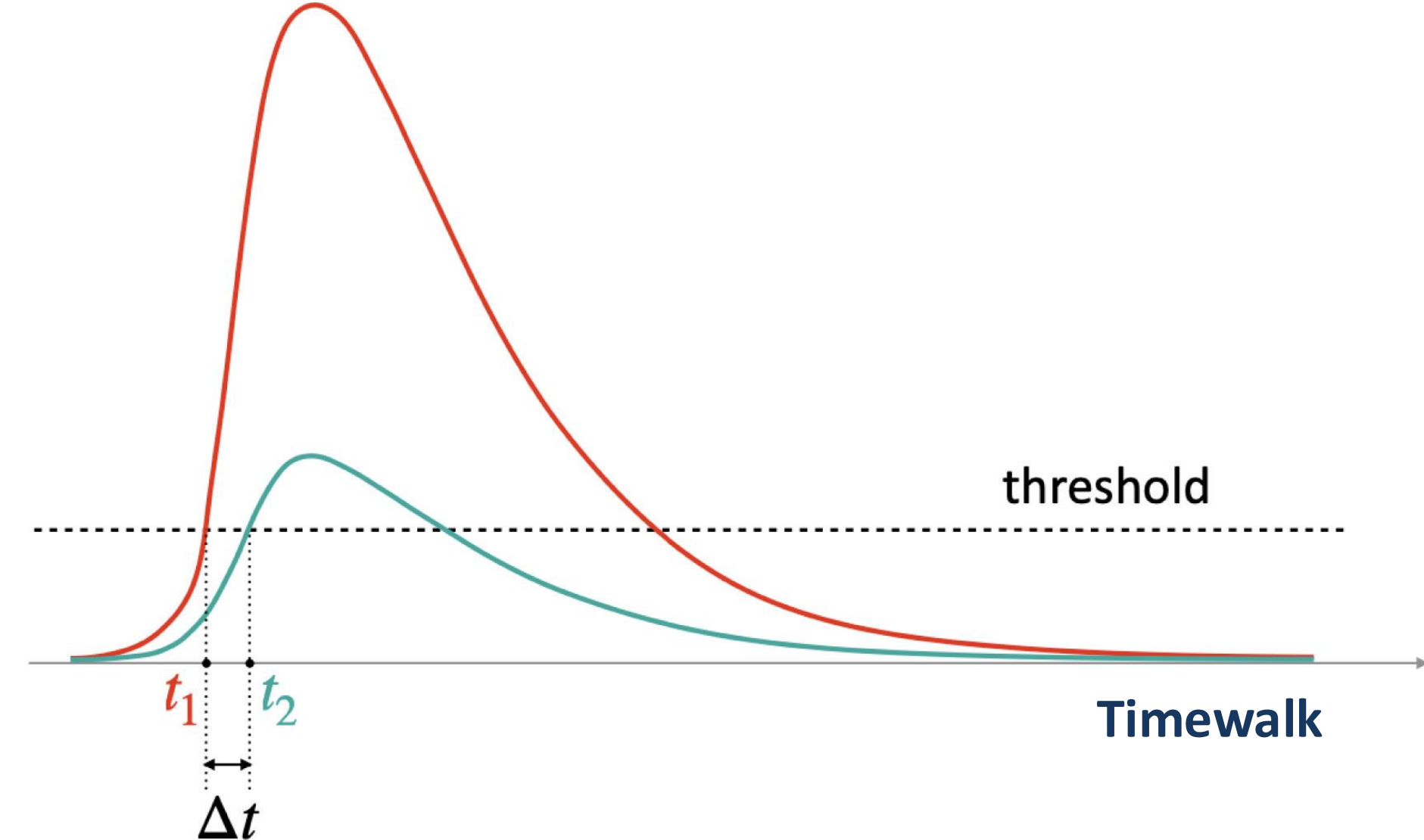
S. Grinstein, TREDI 2025

Timing in HGTD

Contributions to Timing Resolution

- **Landau distribution:** non-uniform energy deposition by MIPs
 - Mitigated by thin active sensor thickness
 - $\sigma_{\text{Landau}} \sim 30 \text{ ps}$
- **Time-walk:** ToA dependency on signal amplitude
 - Corrected using ToT information
 - $\sigma_{\text{Time-walk}} = \frac{V_{th}}{\text{Signal}/t_{rise}} |_{RMS}$
- **Electronic jitter:** electronic noise in the signal amplitude
 - $\sigma_{\text{Jitter}} = \frac{t_{rise}}{\text{Signal}/\text{Noise}} \sim 25 \text{ ps}$

$$\sigma_{\text{Total}}^2 = \underbrace{\sigma_{\text{Landau}}^2}_{\text{SENSOR}} + \underbrace{\sigma_{\text{Timewalk}}^2 + \sigma_{\text{Jitter}}^2 + \sigma_{\text{Clock}}^2 + \sigma_{\text{TDC}}^2}_{\text{ELECTRONICS}}$$



<https://doi.org/10.1016/j.physrep.2025.10.006>

Experimental setup: HGTD test-beam campaigns

- HGTD modules are characterised through two complementary test-beam campaigns
- The results presented in this work are obtained from the October 2025 CERN SPS test-beam campaign



Figure 5: Test-beam setup at DESY (Germany)

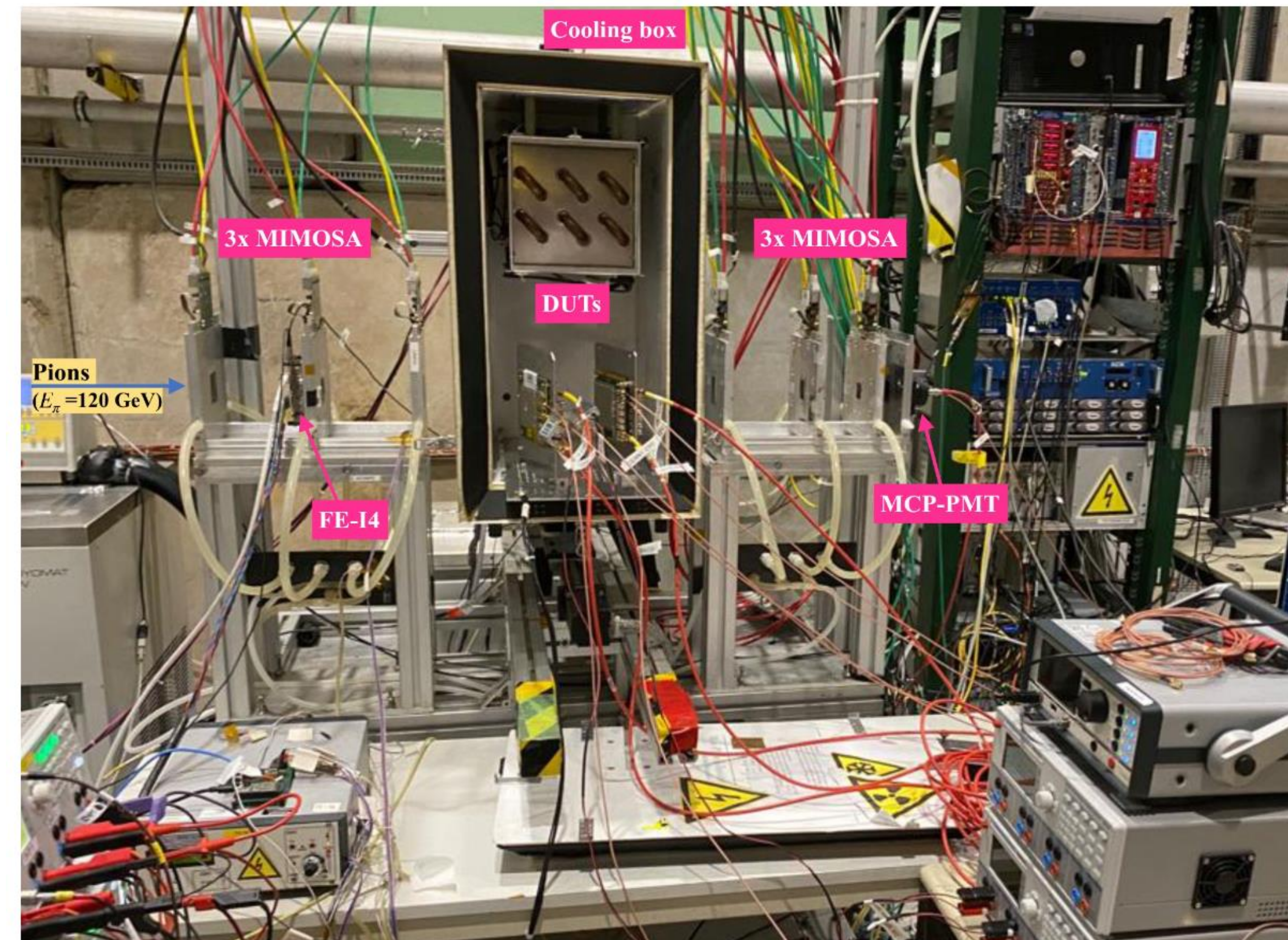


Figure 6: Test-beam setup at SPS CERN

Experimental setup: Test-beam workflow

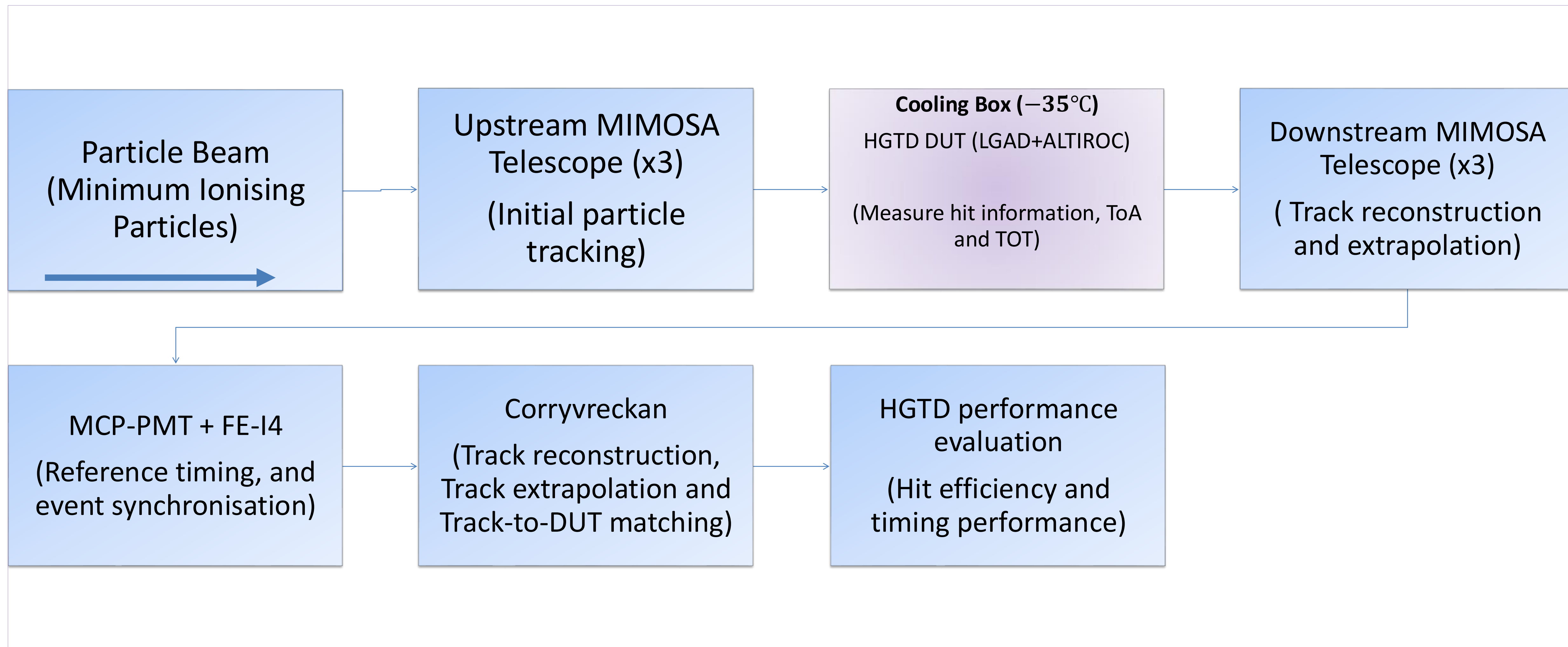


Figure 7: Schematic overview of the CERN SPS HGTD test-beam workflow

Test-beam measurements

Hit Efficiency

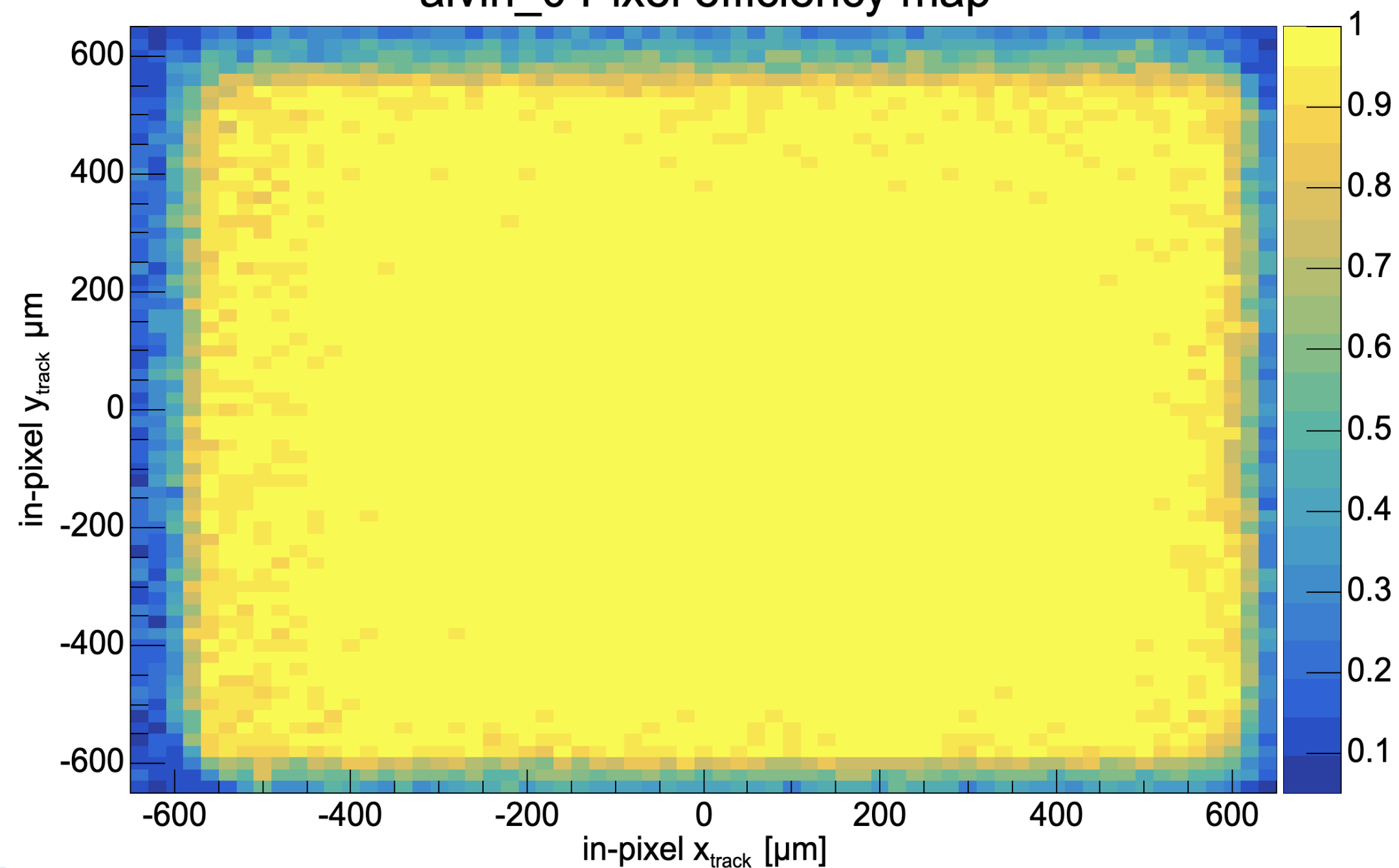
Test-beam measurements with Alvin on ALTIROC-A modules at CERN SPS

- Batch **217**:
 - Highly uniform detector response across the active pixel
 - 98% in the gain region, exceeding HGTD design target

ATLAS HGTD Test Beam Preliminary

October 2025, FM03/B3W1 sensor, Chip 0 (HV: 100 V, T: -35°C , Threshold: 4 fC)

alvin_0 Pixel efficiency map

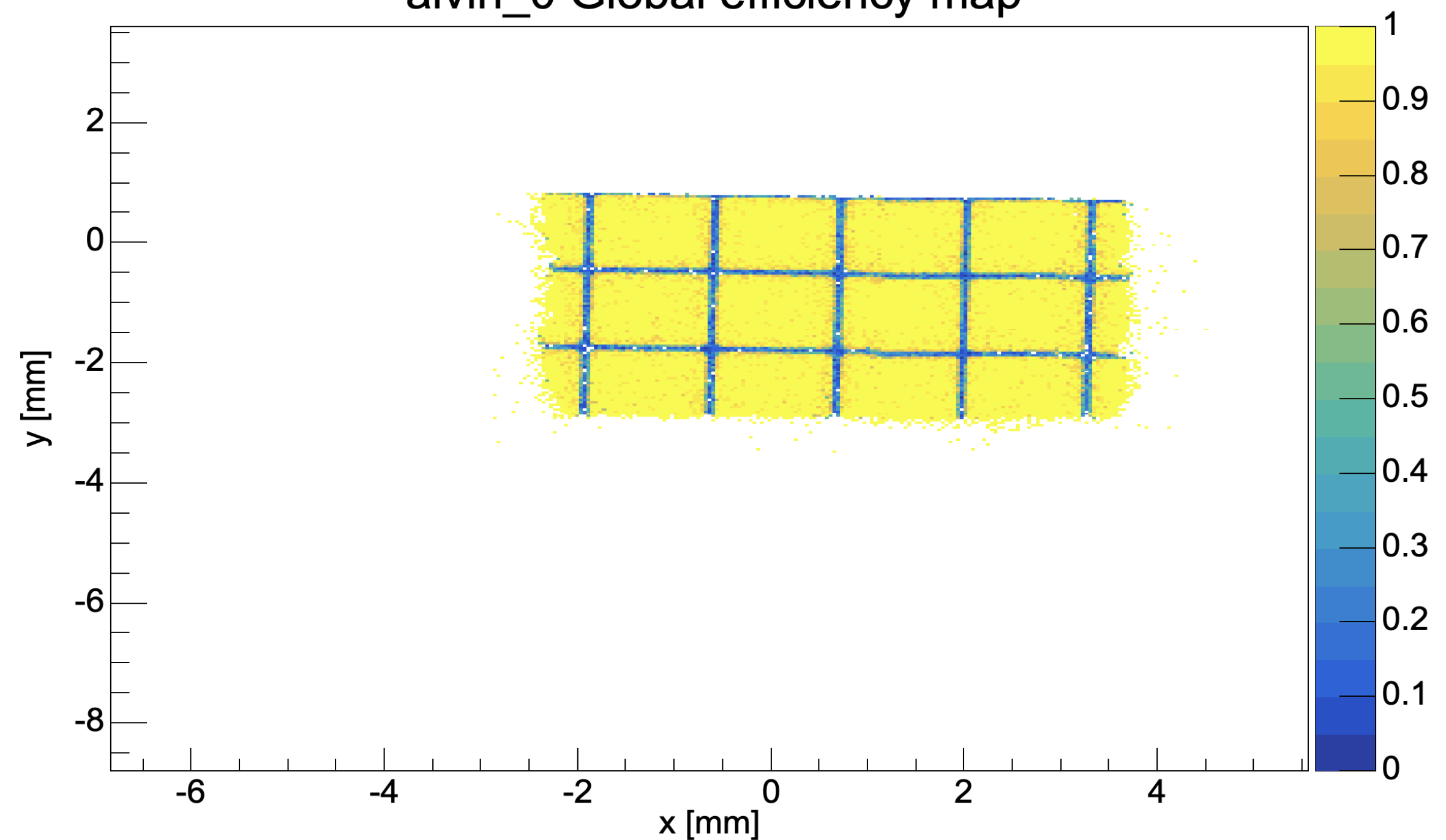


a) In-pixel efficiency map

ATLAS HGTD Test Beam Preliminary

October 2025, FM03/B3W1 sensor, Chip 0 (HV: 100 V, T: -35°C , Threshold: 4 fC)

alvin_0 Global efficiency map



b) Global efficiency map

Test-beam measurements

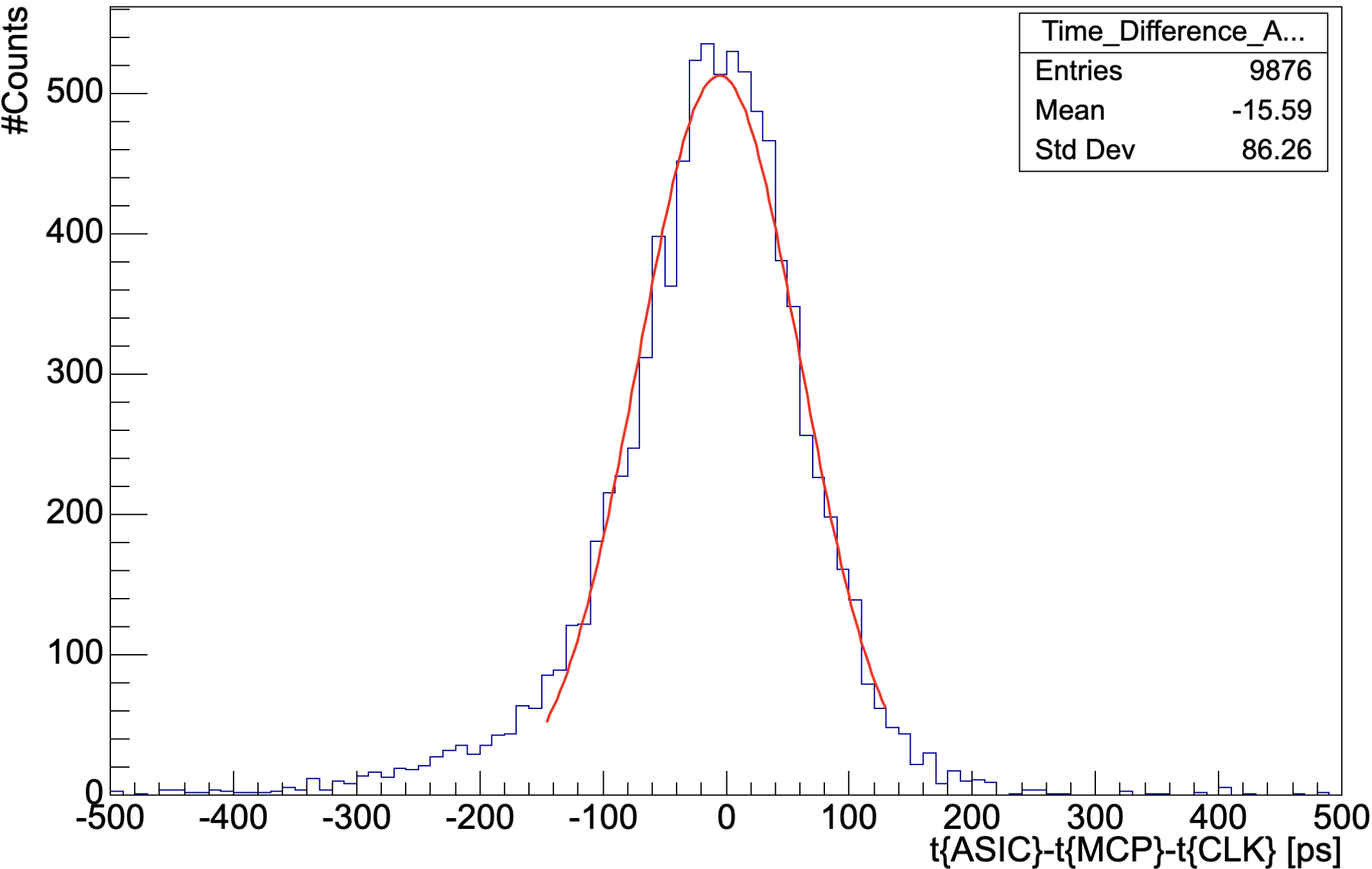
Timing Performance

- Module tuned at threshold 4 fC and with bias voltage from 90 V to 100 V
- Measurement performed at -35°C
- Results shown after time-walk corrections

ATLAS HGTD Test Beam Preliminary

October2025, FM03/B3W1 sensor, Chip 0 (HV: 100 V, T: -35°C, Threshold: 4 fC)

Time_Difference_ASIC_to_MCP

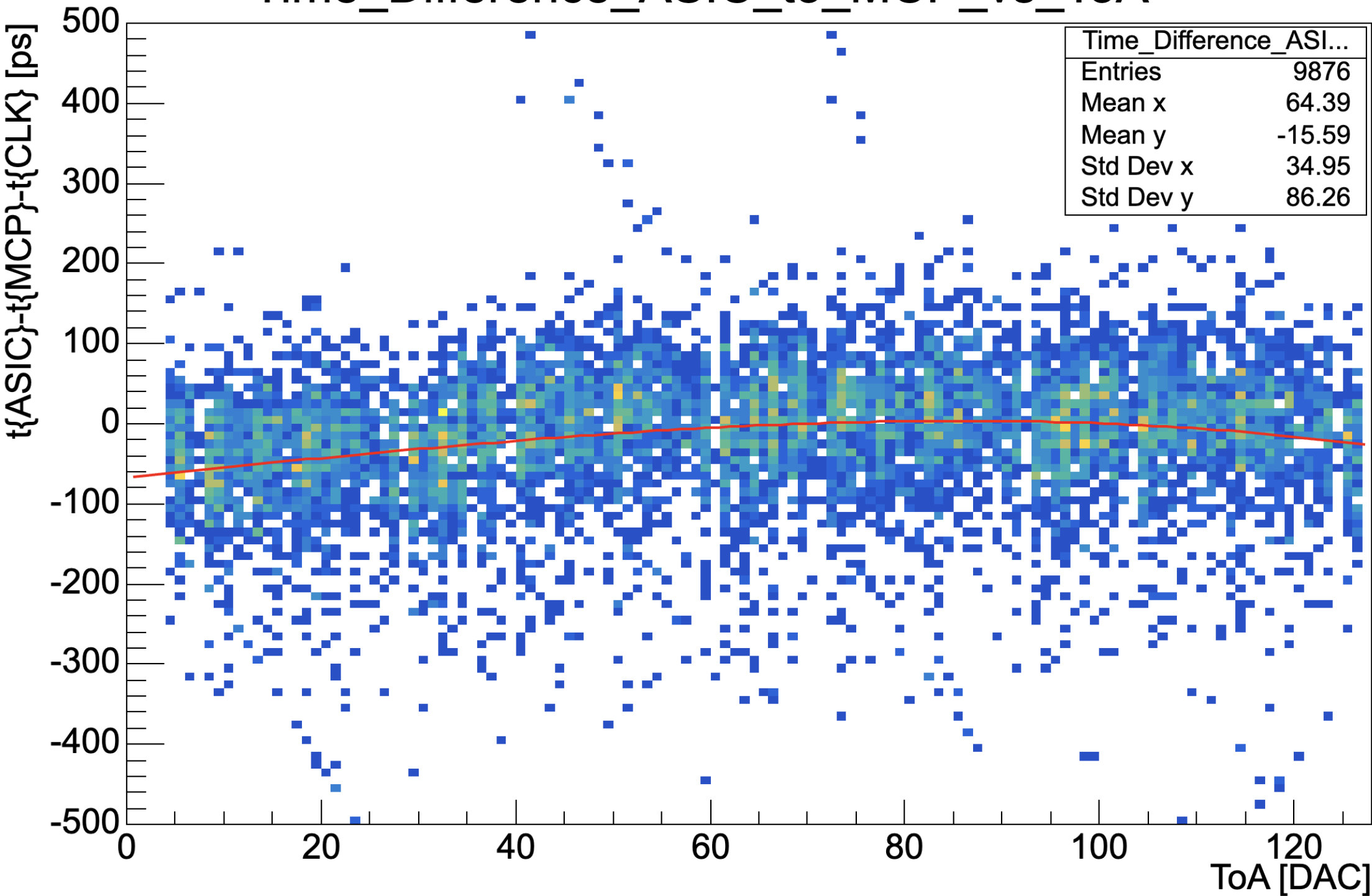


a) The corrected time difference between the DUT and the MCP-PMT reference detector

ATLAS HGTD Test Beam Preliminary

October2025, FM03/B3W1 sensor, Chip 0 (HV: 100 V, T: -35°C, Threshold: 4 fC)

Time_Difference_ASIC_to_MCP_vs_ToA



b) Residual Time Difference vs ToA

Test-beam measurements

Hit Efficiency

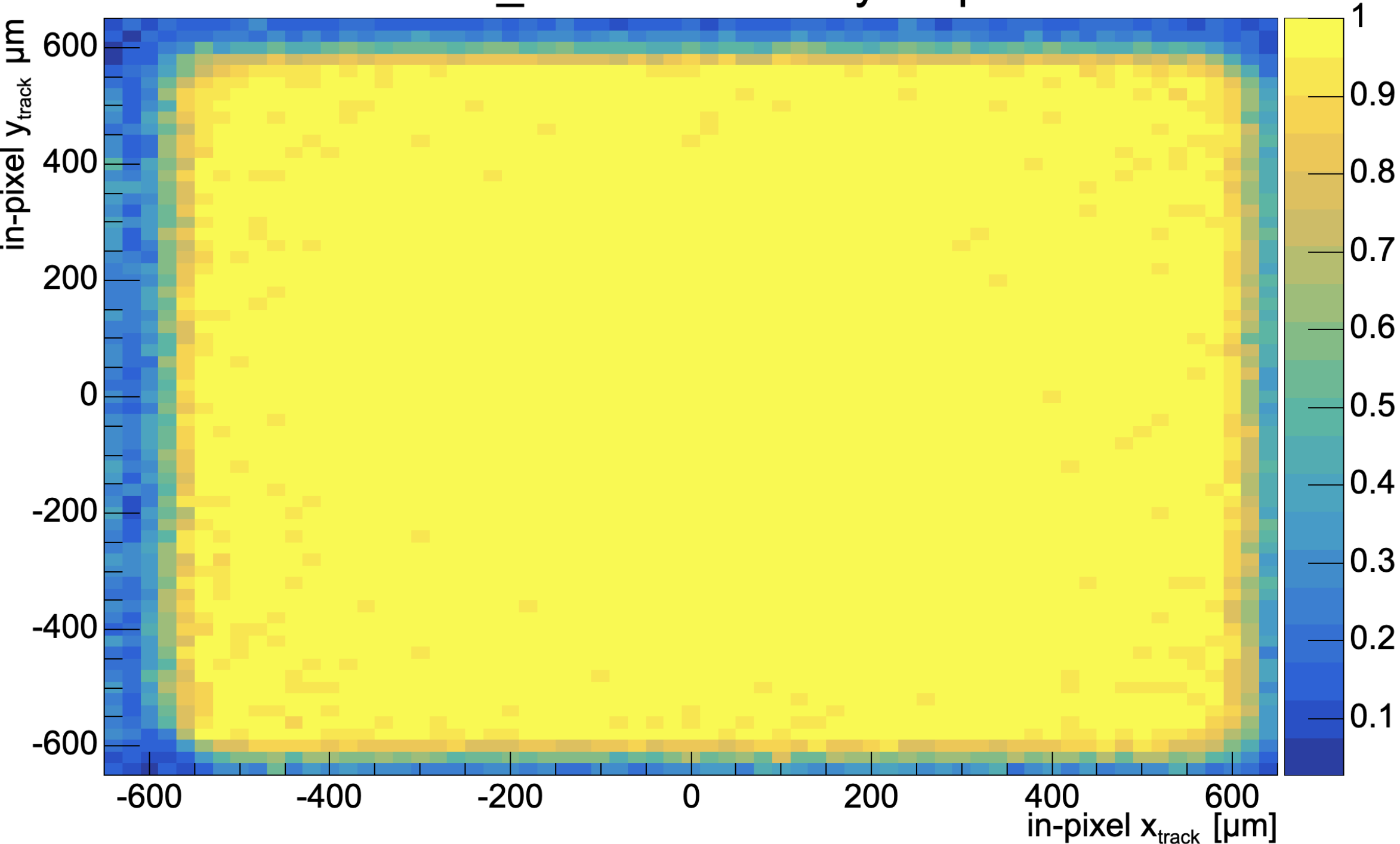
Test-beam measurements with Alvin on ALTIROC-A modules at CERN SPS

□ Batch 218:

ATLAS HGTD Test Beam Preliminary

October2025, FM03/B3W1 sensor, Chip 0 (HV: 110 V, T: -35°C , Threshold: 4 fC)

alvin_0 Pixel efficiency map

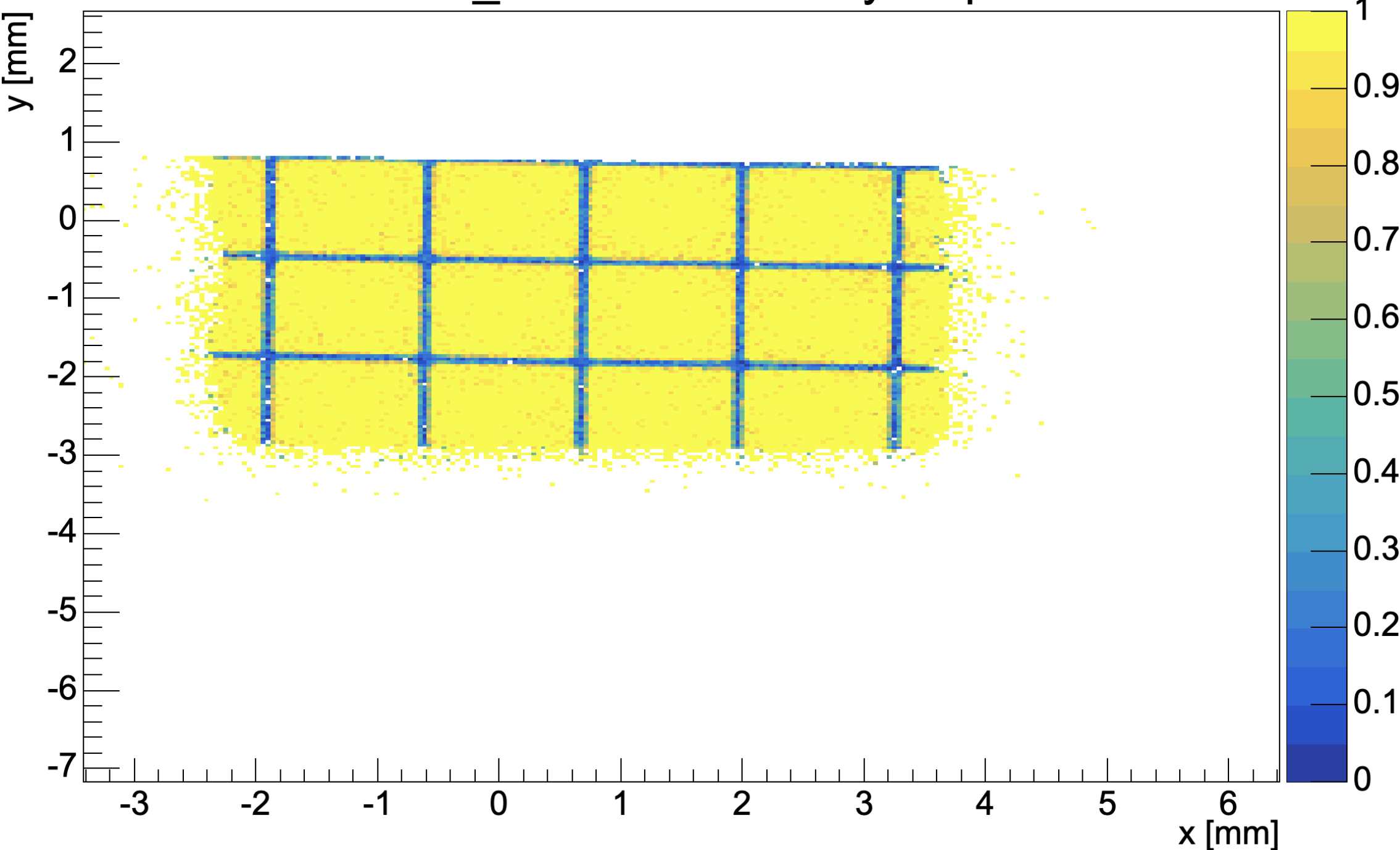


a) In-pixel efficiency map

ATLAS HGTD Test Beam Preliminary

October2025, FM03/B3W1 sensor, Chip 0 (HV: 110 V, T: -35°C , Threshold: 4 fC)

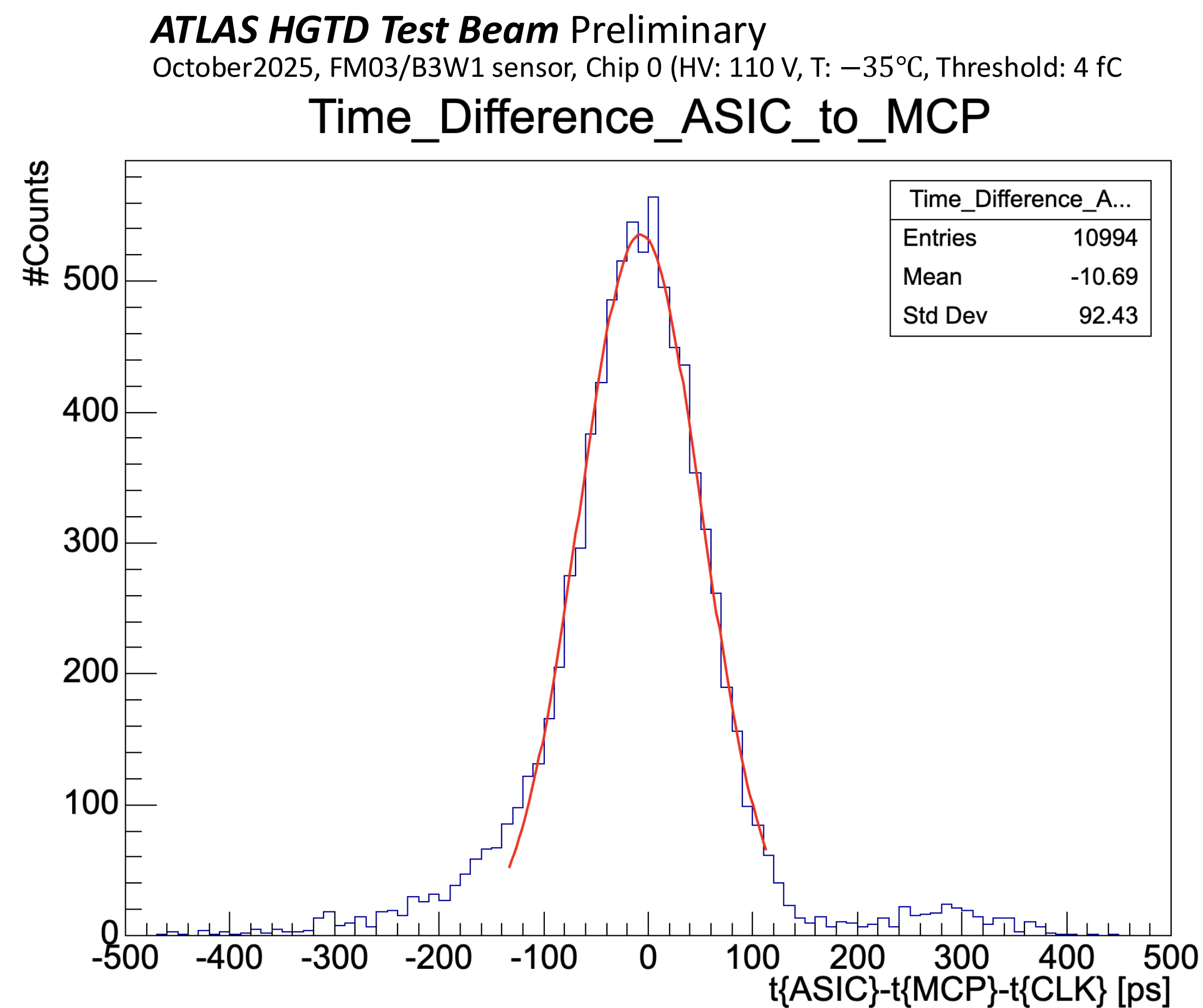
alvin_0 Global efficiency map



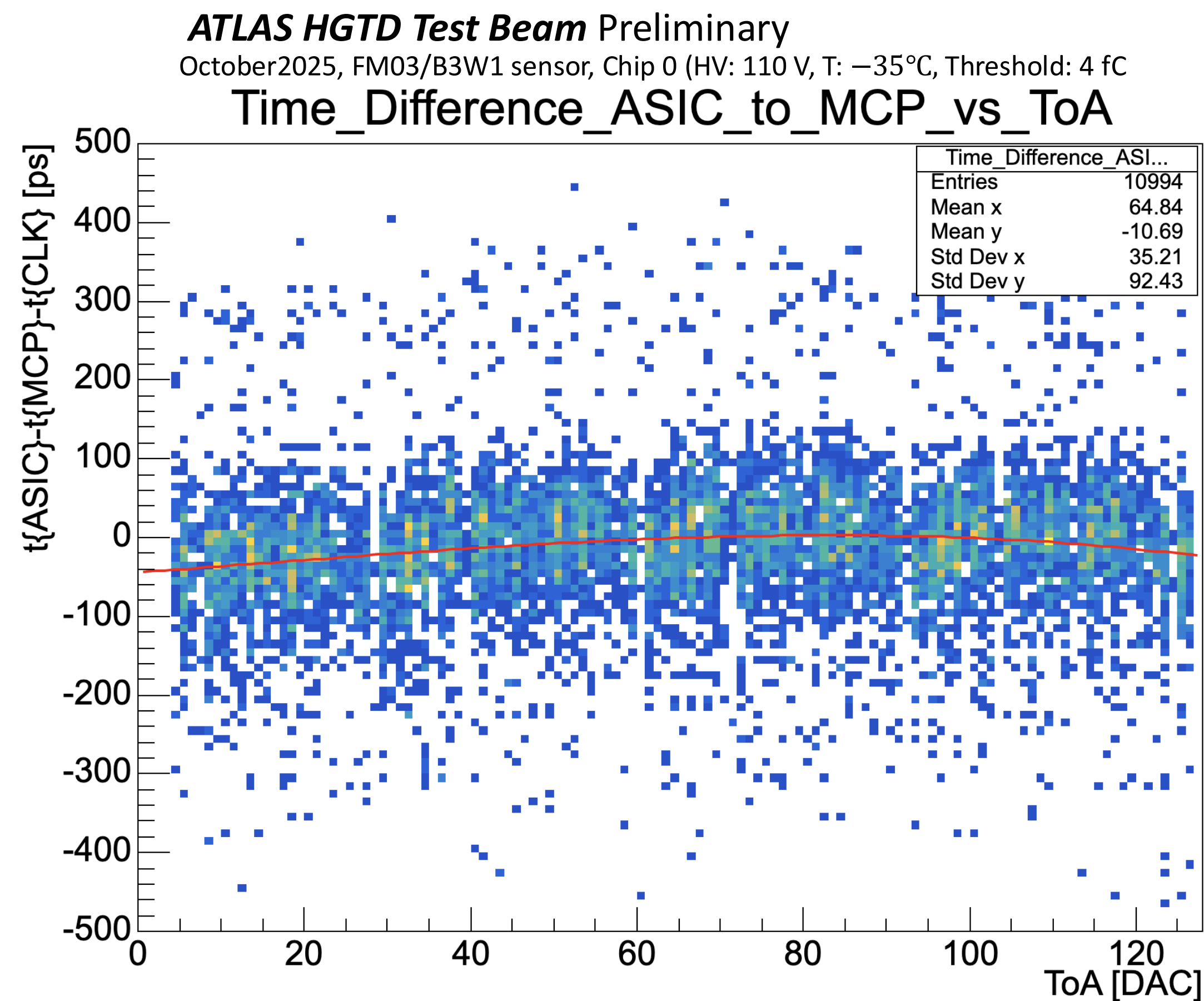
b) Global efficiency map

Test-beam measurements

- Module tuned at threshold 4 fC and with bias voltage from 90 V to 100 V
- Measurement performed at -35°C
- Results shown after time-walk and MCP corrections



a) The time difference between the DUT and the MCP-PMT reference detector

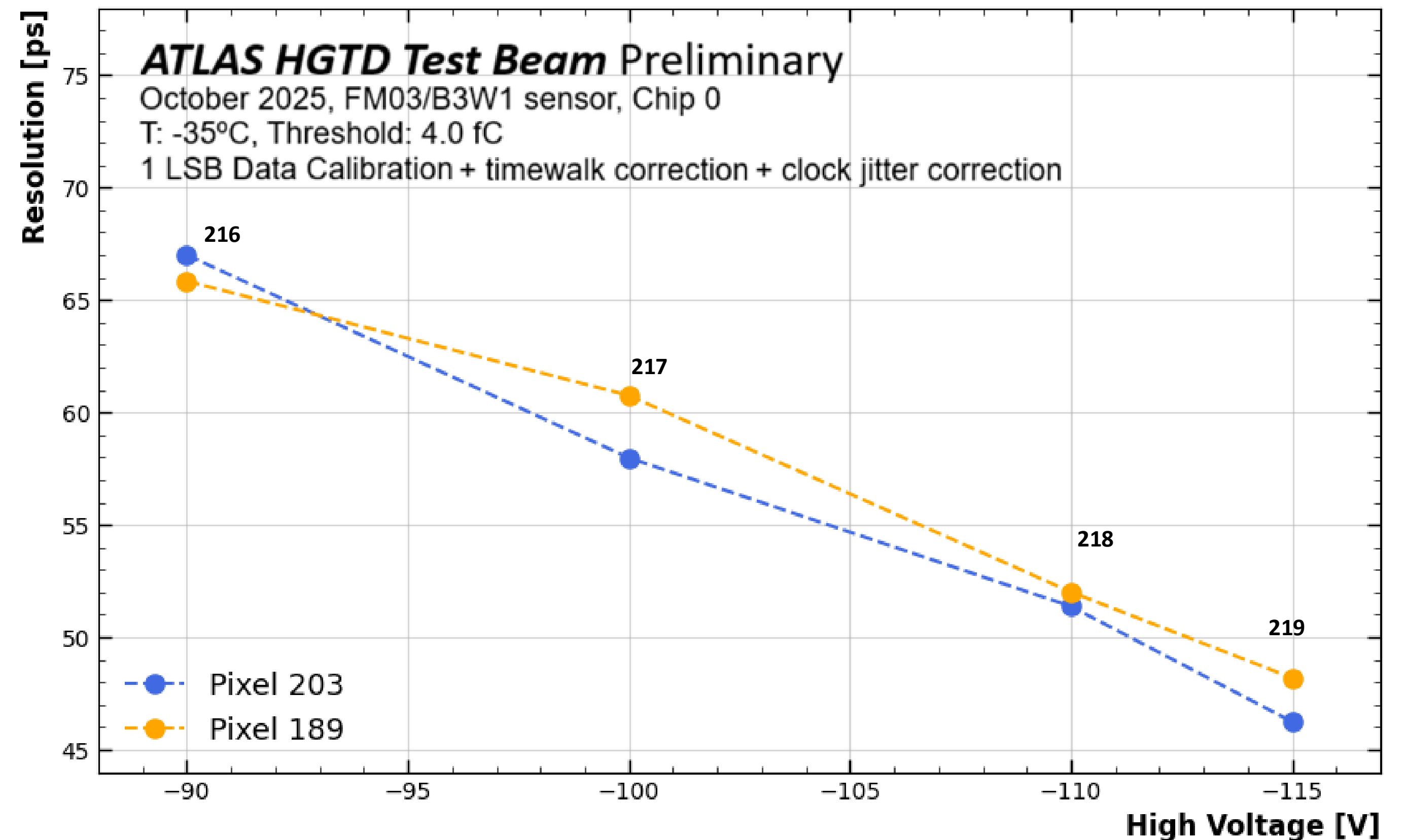


b) Residual Time Difference vs ToA

Test-beam measurements

Timing Performance

- Summarises the timing performance across batch 216-219
- Evaluate the consistency and reproducibility
- **Increasing |HV| improves the time resolution** (lower resolution values are better)
- Both pixels show **consistent behaviour**, demonstrating good reproducibility
- Best measured resolution reaches $\approx 46\text{--}48\text{ ps}$ at -115V , approaching the HGTD design target



a) Time resolution as a function of high voltage for pixels 189 and 203 (batches 216–219)

Credit: Pau Fuste Martin

Conclusions

- HGTD will **mitigate** the **pile-up effects** for the HL-LHC
 - Thanks to LGAD technology for its time resolution
- **Module assembly and testing procedure** established
 - Pre-production ongoing with more than 50 functional modules
- Full **ALTIROC-A modules tested at test beam**
 - Hit efficiency of above 98% in the gain region
 - Time resolution below 50 ps

Future work:

- Plans to continue **testing modules at future test beams**
 - Testing of irradiated modules, for the first time

Thank you

Back-up slides

The pile-up will be caused by the increase of the instantaneous luminosity

- Pile-up $\langle u \rangle = 200$ interactions per bunch crossing, spread in ~ 45 mm along the beam axis.
- The **Inner Tracker (ITk)** mostly mitigates the pile-up effect but is still challenging in the forward region.
- To discriminate between pile-up and hard scattering interaction, the HGTD will be added in the forward region with the goal to have 30-50 ps per track time resolution (beginning-end).
- By utilizing both spatial and timing information, we can confidently link tracks to vertices in the forward region.

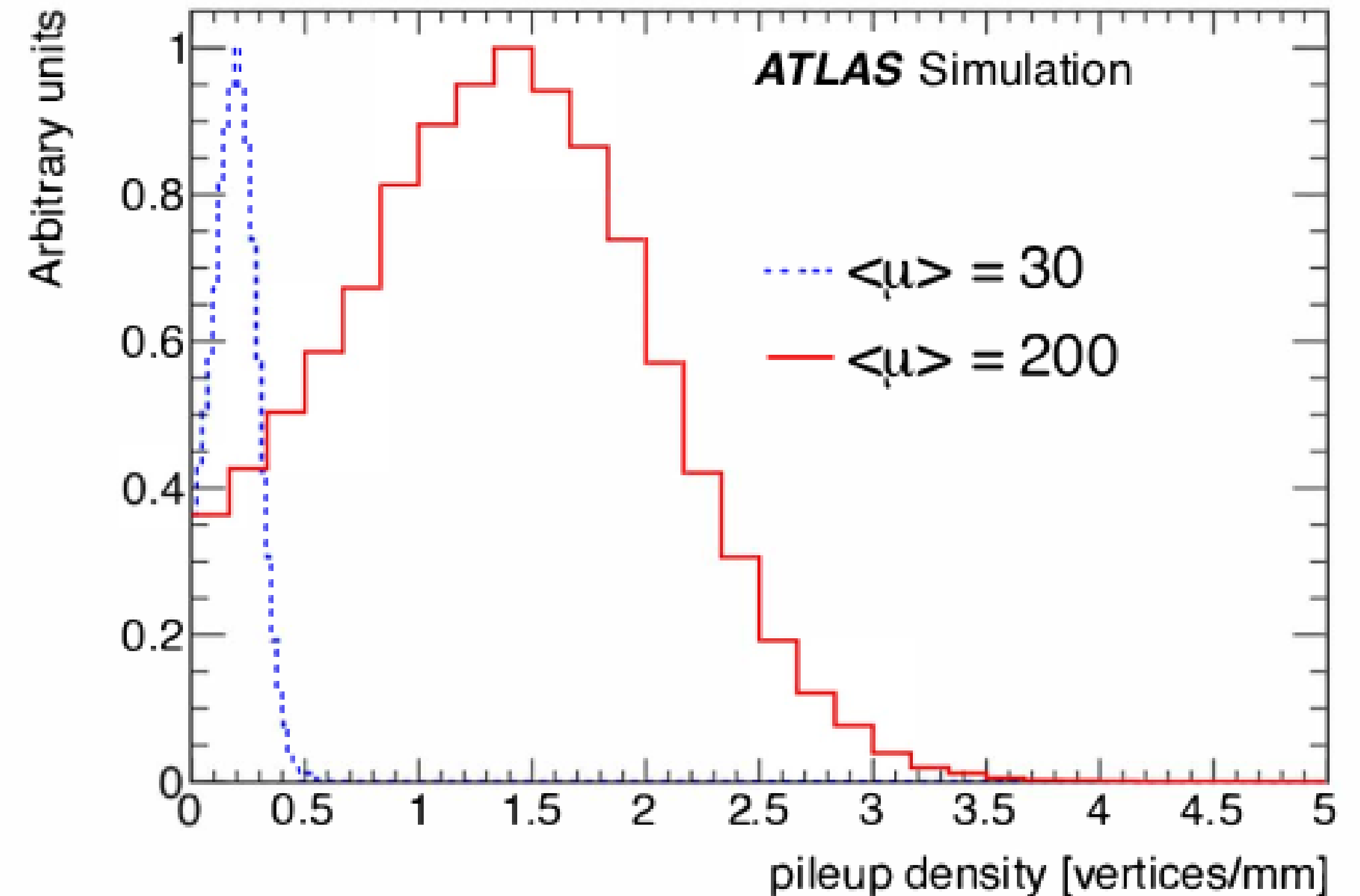


Figure: Pile-up differences